

ITU-T G.8262 SYNCHRONOUS ETHERNET JITTER-ATTENUATING CLOCK MULTIPLIER

Features

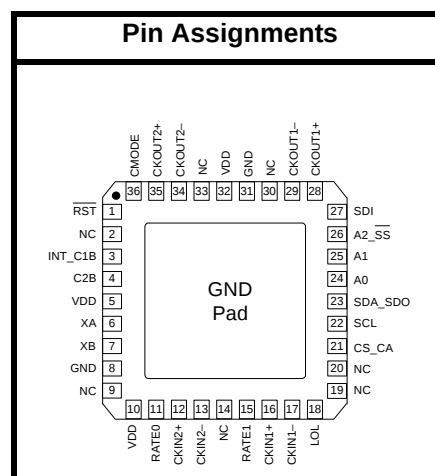
- Fully-compliant with ITU-T G.8262, EEC options 1 and 2.
- Generates any frequency from 8 kHz to 808 MHz.
- Ultra-low jitter clock outputs with jitter generation as low as 0.3 ps rms (12 kHz–20 MHz)
- Integrated loop filter with selectable loop bandwidth (0.1 Hz; 1 to 10 Hz)
- Dual clock inputs with manual or automatically controlled hitless switching
- Dual clock outputs with selectable signal format (LVPECL, LVDS, CML, CMOS)
- LOL, LOS, FOS alarm outputs
- I²C or SPI programmable
- On-chip voltage regulator for 2.5 $\pm$ 10% or 3.3 V $\pm$ 10% operation
- Small size: 6 x 6 mm 36-lead QFN
- Pb-free, ROHS compliant

Applications

- G.8262 Synchronous Ethernet, EEC options 1 and 2
- GbE/10GbE/100GbE Synchronous Ethernet
- Carrier Ethernet switches, routers

Description

The Si5328 is a jitter-attenuating precision clock multiplier for Synchronous Ethernet applications requiring sub 1 ps jitter performance and ultra-low loop bandwidth. When combined with a low-wander, low-jitter reference oscillator, the Si5328 meets all of the wander, MTIE, TDEV, and other requirements listed in ITU-T G.8262/Y.1362. The Si5328 accepts two input clocks ranging from 8 kHz to 710 MHz and generates two output clocks ranging from 8 kHz to 808 MHz. The two outputs are divided down separately from a common source. The Si5328 can also use the TCXO as a clock source for frequency synthesis. The device provides virtually any frequency translation combination across this operating range. The Si5328 input clock frequency and clock multiplication ratio are programmable through an I²C or SPI interface. The Si5328 is based on Silicon Laboratories' third-generation DSPLL[®] technology, which provides frequency synthesis and jitter attenuation in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The DSPLL loop bandwidth is digitally programmable, providing jitter performance optimization at the application level. Operating from a single 2.5 or 3.3 V supply, the Si5328 is ideal for providing clock multiplication and jitter attenuation in high-performance, Synchronous Ethernet timing applications.



Functional Block Diagram

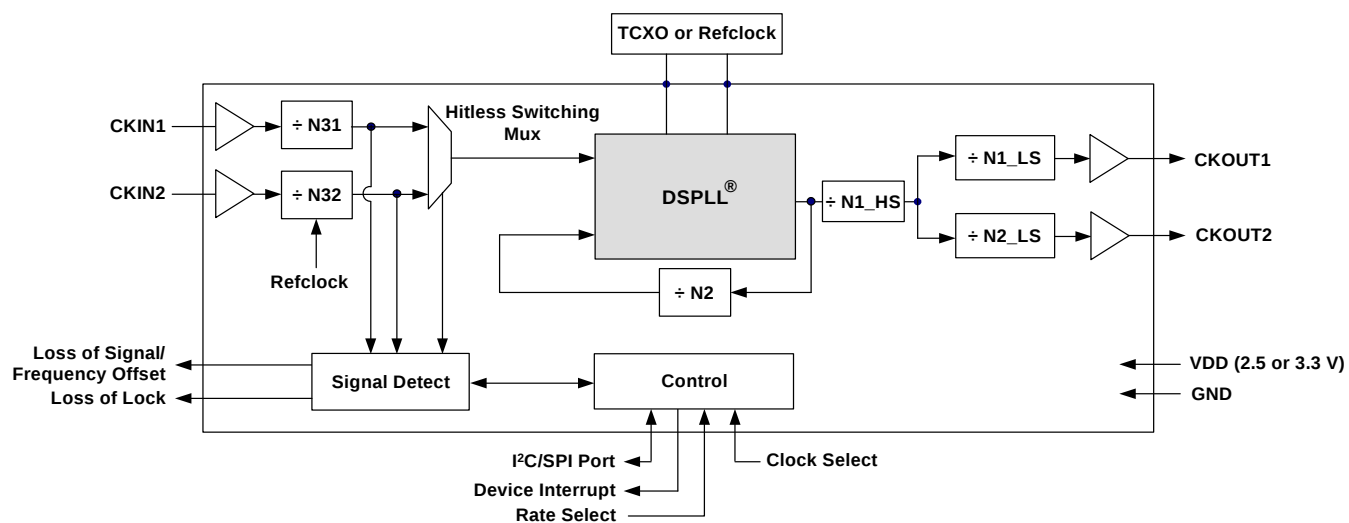


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1. Electrical Specifications

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Ambient Temperature	T_A		-40	25	85	C
Supply Voltage during Normal Operation	V_{DD}	3.3 V Nominal	2.97	3.3	3.63	V
		2.5 V Nominal	2.25	2.5	2.75	V

Note: All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions. Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise stated.

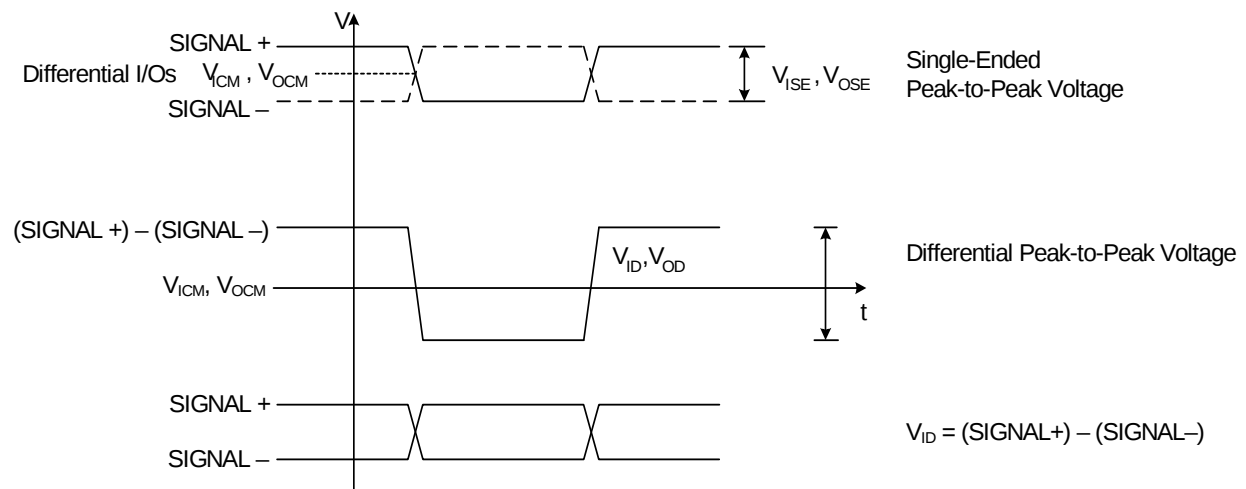


Figure 1. Differential Voltage Characteristics

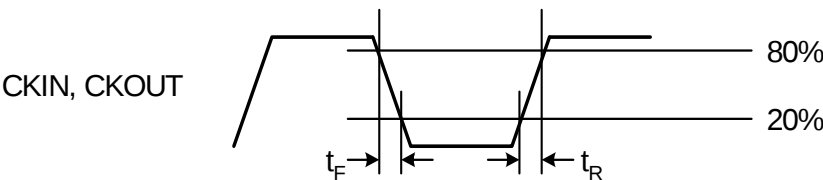


Figure 2. Rise/Fall Time Characteristics

Table 2. DC Characteristics(V_{DD} = 2.5 V ±10% or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply Current ¹	I _{DD}	LVPECL Format 808 MHz Out Both CKOUTs Enabled	—	251	279	mA
		LVPECL Format 808 MHz Out 1 CKOUT Enabled	—	217	243	mA
		CMOS Format 25 MHz Out Both CKOUTs Enabled	—	204	234	mA
		CMOS Format 25 MHz Out 1 CKOUT Enabled	—	194	220	mA
		Disable Mode	—	165	—	mA
CKINn Input Pins ²						
Input Common Mode Voltage (Input Thresh- old Voltage)	V _{ICM}	2.5 V ± 10%	1	—	1.7	V
		3.3 V ± 10%	1.1	—	1.95	V
Input Resistance	CKN _{RIN}	Single-ended	20	40	60	kΩ
Single-Ended Input Voltage Swing (See Absolute Specs)	V _{ISE}	f _{CKIN} < 212.5 MHz See Figure 1.	0.2	—	—	V _{PP}
		f _{CKIN} > 212.5 MHz See Figure 1.	0.25	—	—	V _{PP}
Differential Input Voltage Swing (See Absolute Specs)	V _{ID}	f _{CKIN} < 212.5 MHz See Figure 1.	0.2	—	—	V _{PP}
		f _{CKIN} > 212.5 MHz See Figure 1.	0.25	—	—	V _{PP}
Notes: 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 312.5 MHz. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.						

Table 2. DC Characteristics (Continued)(V_{DD} = 2.5 V ±10% or 3.3 V ±10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Clocks (CKOUTn)						
Common Mode	CKO _{VCM}	LVPECL 100 Ω load line-to-line	V _{DD} -1.42	—	V _{DD} -1.25	V
Differential Output Swing ³	CKO _{VD}	LVPECL 100 Ω load line-to-line	1.1	—	1.9	V _{PP}
Single Ended Output Swing ³	CKO _{VSE}	LVPECL 100 Ω load line-to-line	0.5	—	0.93	V _{PP}
Differential Output Voltage ³	CKO _{VD}	CML 100 Ω load line-to-line	350	425	500	mV _{PP}
Common Mode Output Voltage ³	CKO _{VCM}	CML 100 Ω load line-to-line	—	V _{DD} -0.36	—	V
Differential Output Voltage ³	CKO _{VD}	LVDS 100 Ω load line-to-line	500	700	900	mV _{PP}
		Low Swing LVDS 100 Ω load line-to-line	350	425	500	mV _{PP}
Common Mode Output Voltage ³	CKO _{VCM}	LVDS 100 Ω load line-to-line	1.125	1.2	1.275	V
Differential Output Resistance	CKO _{RD}	CML, LVPECL, LVDS	—	200	—	Ω
Output Voltage Low	CKO _{VOLLH}	CMOS	—	—	0.4	V
Output Voltage High	CKO _{VOHLH}	V _{DD} = 2.25 V CMOS	0.8 x V _{DD}	—	—	V
Notes: 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 312.5 MHz. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.						

Table 2. DC Characteristics (Continued)(V_{DD} = 2.5 V ±10% or 3.3 V ±10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Drive Current (CMOS driving into CKO _{VOL} for output low or CKO _{VOH} for output high. CKOUT+ and CKOUT– shorted externally)	CKO _{IO}	ICMOS[1:0] =11 V _{DD} = 2.5 V	—	20	—	mA
		ICMOS[1:0] =10 V _{DD} = 2.5 V	—	15	—	mA
		ICMOS[1:0] =01 V _{DD} = 2.5 V	—	10	—	mA
		ICMOS[1:0] =00 V _{DD} = 2.5 V	—	5	—	mA
		ICMOS[1:0] = 11 V _{DD} = 3.3 V	—	32	—	mA
		ICMOS[1:0] =10 V _{DD} = 3.3 V	—	24	—	mA
		ICMOS[1:0] =01 V _{DD} = 3.3 V	—	16	—	mA
		ICMOS[1:0] =00 V _{DD} = 3.3 V	—	8	—	mA
2-Level LVCMOS Input Pins						
Input Voltage Low	V _{IL}	V _{DD} = 2.25 V	—	—	0.7	V
		V _{DD} = 2.97 V	—	—	0.8	V
Input Voltage High	V _{IH}	V _{DD} = 2.25 V	1.8	—	—	V
		V _{DD} = 3.63 V	2.5	—	—	V
Notes:						
1. Current draw is independent of supply voltage						
2. No under- or overshoot is allowed.						
3. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 312.5 MHz.						
4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.						

Table 2. DC Characteristics (Continued)(V_{DD} = 2.5 V ±10% or 3.3 V ±10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
3-Level Input Pins⁴						
Input Voltage Low	V _{ILL}		—	—	0.15 x V _{DD}	V
Input Voltage Mid	V _{IMM}		0.45 x V _{DD}	—	0.55 x V _{DD}	V
Input Voltage High	V _{IHH}		0.85 x V _{DD}	—	—	V
Input Low Current	I _{ILL}	See Note 4	-20	—	—	μA
Input Mid Current	I _{IMM}	See Note 4	-2	—	+2	μA
Input High Current	I _{IHH}	See Note 4	—	—	20	μA
LVC MOS Output Pins						
Output Voltage Low	V _{OL}	IO = 2 mA V _{DD} = 2.25 V	—	—	0.4	V
Output Voltage Low		IO = 2 mA V _{DD} = 2.97 V	—	—	0.4	V
Output Voltage High	V _{OH}	IO = -2 mA V _{DD} = 2.25 V	V _{DD} - 0.4	—	—	V
Output Voltage High		IO = -2 mA V _{DD} = 2.97 V	V _{DD} - 0.4	—	—	V
Disabled Leakage Current	I _{OZ}	RSTb = 0	-100	—	100	μA
Notes: 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL, CML, LVDS and low-swing LVDS measured with Fo = 312.5 MHz. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.						

Table 3. AC Characteristics(V_{DD} = 2.5 ±10% or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Single-Ended Reference Clock Input Pin XA (XB with cap to GND)						
Input Resistance	XA _{RIN}	RATE[1:0] = LM, ML, MH, ac coupled	—	12	—	kΩ
Input Voltage Swing	XA _{VPP}	RATE[1:0] = LM, ML, MH, ac coupled	0.5	—	1.2	V _{PP}
Differential Reference Clock Input Pins (XA/XB)						
Input Voltage Swing	XA/XB _{VPP}	RATE[1:0] = LM, ML, MH	0.5	—	1.2	V _{PP} , each.
CKINn Input Pins						
Input Frequency	CKN _F		0.008	—	710	MHz
Input Duty Cycle (Minimum Pulse Width)	CKN _{DC}	Input frequency > 225 MHz	40	—	60	%
		Input frequency < 225 MHz refers to both high and low widths	2	—	—	ns
Input Capacitance	CKN _{CIN}		—	—	3	pF
Input Rise/Fall Time	CKN _{TRF}	20–80% See Figure 2	—	—	11	ns
CKOUTn Output Pins						
(See ordering section for speed grade vs frequency limits)						
Output Frequency (Output not configured for CMOS)	CKO _F	N1 ≥ 6	0.008	—	808	MHz
Maximum Output Frequency in CMOS Format	CKO _F		—	—	212.5	MHz
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO _{TRF}	CMOS Output V _{DD} = 2.25 C _{LOAD} = 5 pF	—	—	8	ns
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO _{TRF}	CMOS Output V _{DD} = 2.97 C _{LOAD} = 5 pF	—	—	2	ns
Notes:						
1. Lock and settle times may change with different f ₃ , loop BW, and VCO frequency values. Contact Silicon Labs for further details.						
2. See Section 9 of “AN775: Si5328 Synchronous Ethernet Compliance Test Report” for more details.						

Table 3. AC Characteristics (Continued)(V_{DD} = 2.5 ±10% or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Rise/Fall (20–80%) @ 312.5 MHz output	CKO _{TRF}	LVPECL, LVDS or CML Output	—	230	350	ps
Output Duty Cycle Uncertainty @ 808 MHz	CKO _{DC}	100 Ω Load Line-to-Line Measured at 50% Point (Not for CMOS)	45	—	55	%
LVC MOS Input Pins						
Minimum Reset Pulse Width	t _{RSTMN}		1			μs
Reset to Microprocessor Access Ready	t _{READY}				10	ms
Input Capacitance	C _{in}		—	—	3	pF
LVC MOS Output Pins						
Rise/Fall Times	t _{RF}	C _{LOAD} = 20pf See Figure 2	—	25	—	ns
LOS _n Trigger Window	LOS _{TRIG}	From last CKIN _n ↑ to ↓ Internal detection of LOS _n N3 ≠ 1	—	—	4.5 x N3	T _{CKIN}
Time to Clear LOL after LOS Cleared	t _{CLRLOL}	↓LOS to ↓LOL Fold = F _{new} Stable Xa/XB reference	—	10	—	ms
Device Skew						
Output Clock Skew	t _{SKEW}	↑ of CKOUT _n to ↑ of CKOUT _m , CKOUT _n and CKOUT _m at same frequency and signal format <u>PHASEOFFSET</u> = 0 <u>CKOUT_ALWAYS_ON</u> = 1 <u>SQ_ICAL</u> = 1	—	—	100	ps
Phase Change due to Temperature Variation	t _{TEMP}	Max phase changes from –40 to +85 °C, stable XAXB reference	—	300	500	ps
Notes: 1. Lock and settle times may change with different f₃, loop BW, and VCO frequency values. Contact Silicon Labs for further details. 2. See Section 9 of “AN775: Si5328 Synchronous Ethernet Compliance Test Report” for more details.						

Table 3. AC Characteristics (Continued)(V_{DD} = 2.5 ±10% or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
PLL Performance (f _{in} = f _{out} = 346 MHz; BW = 0.088 Hz; LVPECL)						
Lock Time ¹	t _{LOCKMP}	Start of ICAL to LOL low, LOCKT = 4, FASTLOCK enabled	—	2	—	s
		Start of ICAL to LOL low, LOCKT = 1, FASTLOCK enabled	—	12.5	—	s
Settle Time ¹	t _{SETTLE}	Start of ICAL to output phase within 45 degrees of final value, LOCKT = 4, FASTLOCK enabled	—	1	—	s
		Start of ICAL to output phase within 45 degrees of final value, LOCKT = 1, FASTLOCK enabled	—	1	—	s
Output Clock Phase Change	t _{P_STEP}	After clock switch f ₃ ≥ 128 kHz	—	200	—	ps
Closed Loop Jitter Peaking	J _{PK}		—	0.05	0.2	dB
Jitter/Wander Tolerance ²	J _{TOL}	Jitter Frequency ≥ Loop Bandwidth	5000/BW	—	—	ns pk-pk
Phase Noise f _{out} = 156.25 MHz	CKO _{PN}	1 kHz Offset	—	–120	—	dBc/Hz
		10 kHz Offset	—	–128	—	dBc/Hz
		100 kHz Offset	—	–130	—	dBc/Hz
		1 MHz Offset	—	–144	—	dBc/Hz
Subharmonic Noise	SP _{SUBH}	Phase Noise @ 100 kHz Offset	—	–88	—	dBc
Spurious Noise	SP _{SPUR}	Max spur @ n x F ₃ (n ≥ 1, n x F ₃ < 100 MHz)	—	–93	—	dBc
Notes: 1. Lock and settle times may change with different f ₃ , loop BW, and VCO frequency values. Contact Silicon Labs for further details. 2. See Section 9 of “AN775: Si5328 Synchronous Ethernet Compliance Test Report” for more details.						

Table 4. Microprocessor Control(V_{DD} = 2.5 ±10% or 3.3 V ±10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
I²C Bus Lines (SDA, SCL)						
Input Voltage Low	V _{IL} I _{2C}		—	—	0.25 × V _{DD}	V
Input Voltage High	V _{IH} I _{2C}		0.7 × V _{DD}	—	V _{DD}	V
Input Current	I _I I _{2C}	V _{IN} = 0.1 × V _{DD} to 0.9 × V _{DD}	-10	—	10	μA
Hysteresis of Schmitt trigger inputs	V _{HYS} I _{2C}		0.05 × V _{DD}	—	—	V
Output Voltage Low	V _{OL} I _{2C}	I _O = 3 mA	—	—	0.4	V

Table 4. Microprocessor Control (Continued)(V_{DD} = 2.5 ±10% or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SPI Specifications						
Duty Cycle, SCLK	t _{DC}	SCLK = 10 MHz	40	—	60	%
Cycle Time, SCLK	t _c		100	—	—	ns
Rise Time, SCLK	t _r	20–80%	—	—	25	ns
Fall Time, SCLK	t _f	20–80%	—	—	25	ns
Low Time, SCLK	t _{lsc}	20–20%	30	—	—	ns
High Time, SCLK	t _{hsc}	80–80%	30	—	—	ns
Delay Time, SCLK Fall to SDO Active	t _{d1}		—	—	25	ns
Delay Time, SCLK Fall to SDO Transition	t _{d2}		—	—	25	ns
Delay Time, SS Rise to SDO Tri-state	t _{d3}		—	—	25	ns
Setup Time, SS to SCLK Fall	t _{su1}		25	—	—	ns
Hold Time, SS to SCLK Rise	t _{h1}		20	—	—	ns
Setup Time, SDI to SCLK Rise	t _{su2}		25	—	—	ns
Hold Time, SDI to SCLK Rise	t _{h2}		20	—	—	ns
Delay Time between Slave Selects	t _{cs}		25	—	—	ns

Table 5. Jitter Generation^{1,2,3,4,5,6}

Symbol	Filter	Output Frequency	Min	Typ	Max	Unit
JGEN	12 kHz to 20 MHz	125 MHz	—	331	—	fs, RMS
JGEN	10 kHz to 1 MHz	125 MHz	—	287	—	fs, RMS
JGEN	12 kHz to 20 MHz	156.25 MHz	—	308	—	fs, RMS
JGEN	10 kHz to 1 MHz	156.25 MHz	—	263	—	fs, RMS

Notes:

1. Input frequency = 25 MHz.
2. XAXB reference = Rakon 40 MHz TCXO model RTX7050A, part number 509768.
3. Vdd = 3.3 V.
4. Clock output = LVPECL.
5. Loop bandwidth = 0.085 Hz.
6. Using Agilent E5052B.

Table 6. Thermal Characteristics(V_{DD} = 2.5 ±10% or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Value	Unit
Thermal Resistance Junction to Ambient	θ_{JA}	Still Air	32	C°/W
Thermal Resistance Junction to Case	θ_{JC}	Still Air	14	C°/W

Table 7. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DC Supply Voltage	V _{DD}		−0.5	—	3.8	V
LVC MOS Input Voltage	V _{DIG}		−0.3		V _{DD} +0.3	V
CKINn Voltage Level Limits	CKN _{VIN}		0	—	V _{DD}	V
XA/XB Voltage Level Limits	XA _{VIN}		0	—	1.2	V
Operating Junction Temperature	T _{JCT}		−55	—	150	°C
Storage Temperature Range	T _{STG}		−55	—	150	°C
ESD HBM Tolerance (100 pF, 1.5 kΩ); All pins except CKIN+/CKIN−			2	—	—	kV
ESD MM Tolerance; All pins except CKIN+/CKIN−			150	—	—	V
ESD HBM Tolerance (100 pF, 1.5 kΩ); CKIN+/CKIN−			750	—	—	V
ESD MM Tolerance; CKIN+/CKIN−			100	—	—	V
Latch-up Tolerance			JESD78 Compliant			
*Note: Permanent device damage may occur if the Absolute Maximum Ratings are exceeded. Functional operation should be restricted to the conditions specified in the operation sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.						

2. Typical Phase Noise Performance

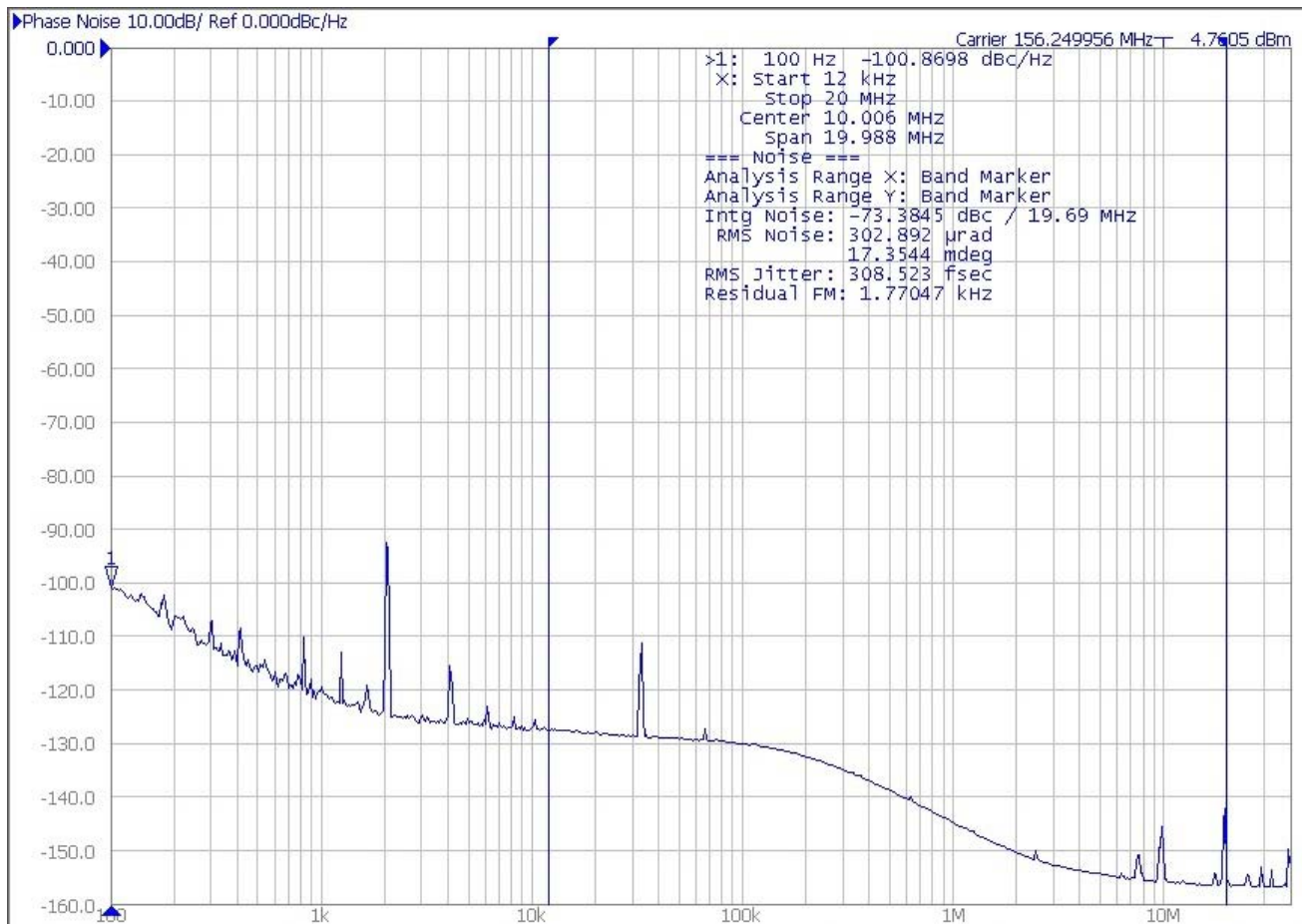


Figure 3. Typical Phase Noise Plot

Table 8. RMS Jitter Values

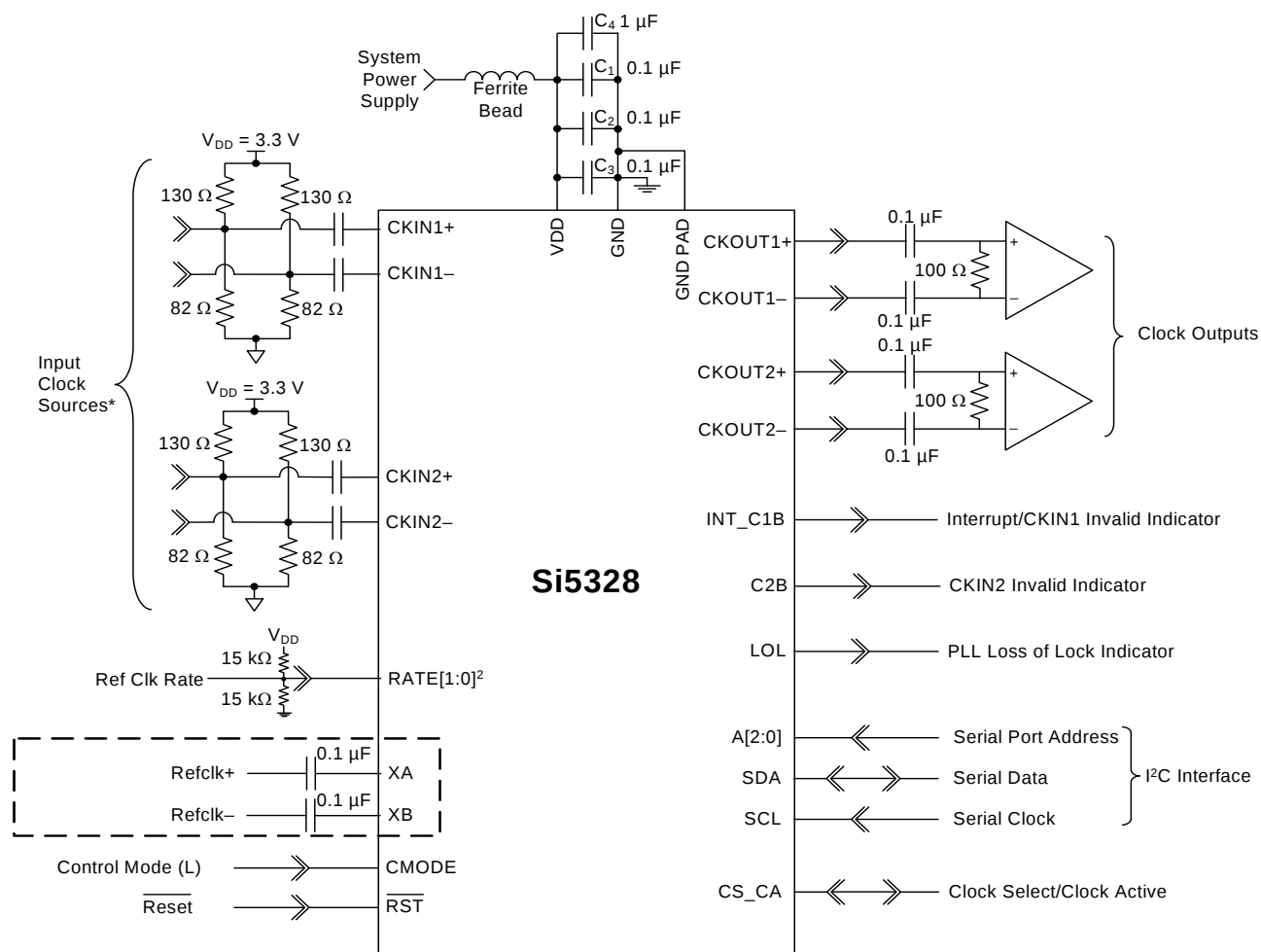
Jitter Band	Jitter (rms)
10 kHz to 1 MHz	263 fs
12 kHz to 20 MHz	309 fs

Notes:

1. input frequency = 25 MHz.
2. XAXB reference = Rakon 40 MHz TCXO model RTX7050A, part number 509768.
3. Vdd = 3.3 V.
4. Clock output = LVPECL.
5. Loop bandwidth = 0.085 Hz.
6. Using Agilent E5052B.

3. Typical Application Circuit

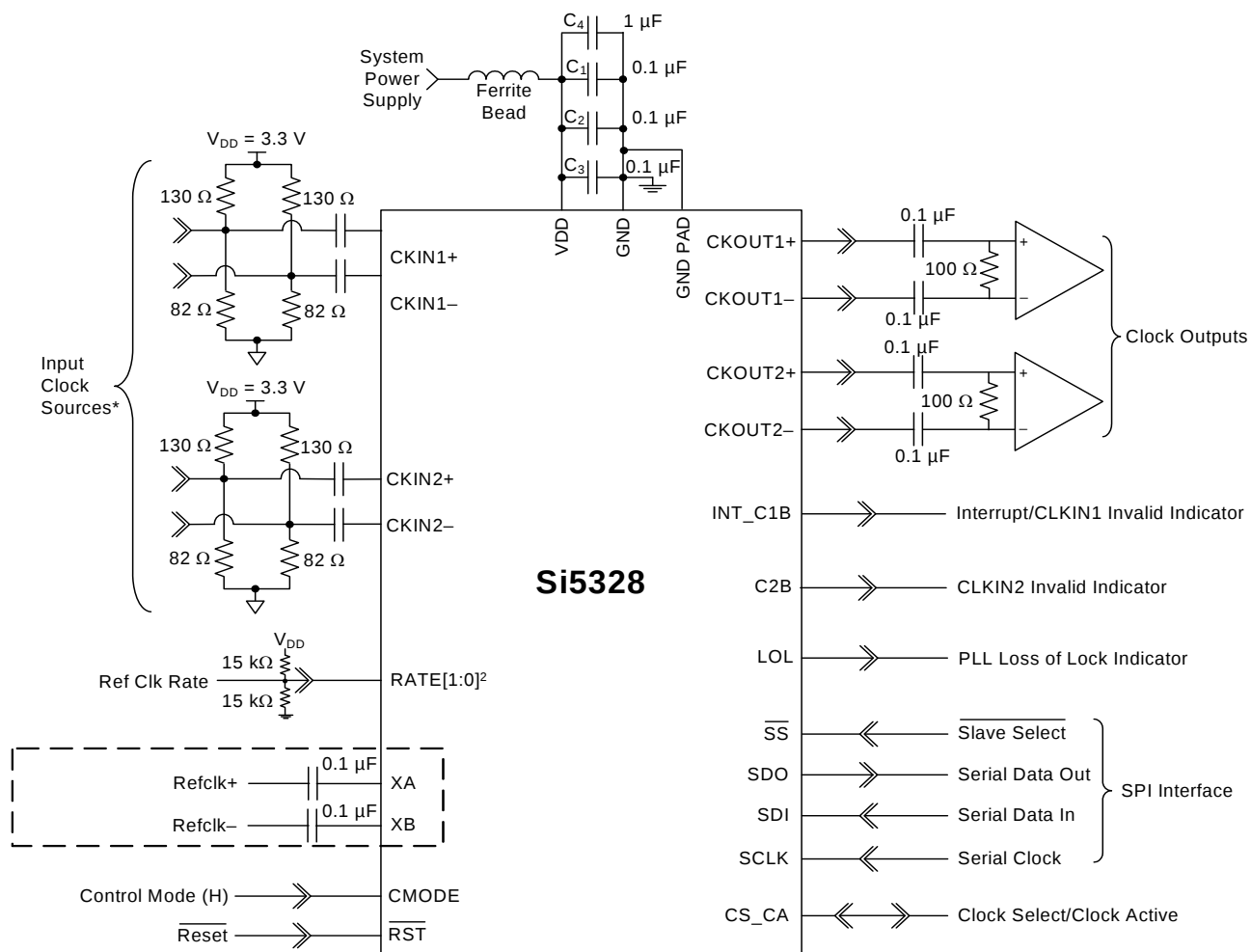
Note: For an example schematic and layout, refer to the Si5328-EVB User's Guide.



Notes:

1. Assumes differential LVPECL termination (3.3 V) on clock inputs.
2. Denotes tri-level input pins with states designated as L (ground), M (V_{DD}/2), and H (V_{DD}).
3. I²C-required pull-up resistors not shown.

Figure 4. Si5328 Typical Application Circuit (I²C Control Mode)



Notes:

1. Assumes differential LVPECL termination (3.3 V) on clock inputs.
2. Denotes tri-level input pins with states designated as L (ground), M ($V_{DD}/2$), and H (V_{DD}).

Figure 5. Si5328 Typical Application Circuit (SPI Control Mode)

4. Functional Description

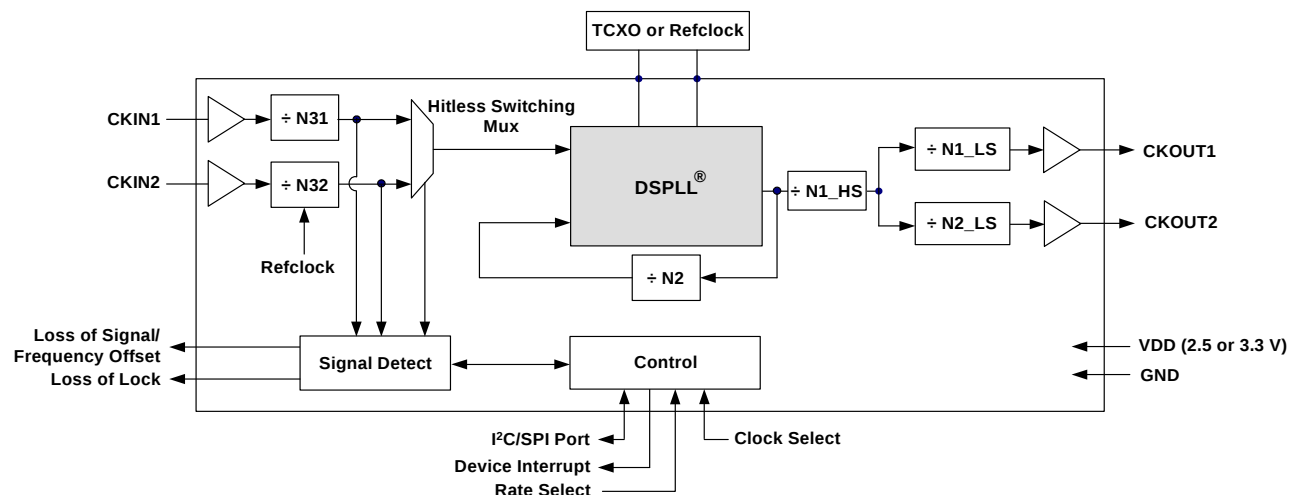


Figure 6. Functional Block Diagram

The Si5328 is a jitter-attenuating precision clock multiplier for Synchronous Ethernet applications requiring sub 1 ps jitter performance and ultra-low loop bandwidth. When combined with a low-wander reference oscillator, the Si5328 meets all of the wander, MTIE, TDEV, and other requirements that are listed in ITU-T G.8262/Y.1362. The Si5328 accepts two input clocks ranging from 8 kHz to 710 MHz and generates two output clocks ranging from 8 kHz to 808 MHz. The Si5328 can also use its TCXO as a clock source for frequency synthesis. The device provides virtually any frequency translation combination across this operating range. Independent dividers are available for each input clock and output clock, so the Si5328 can accept input clocks at different frequencies and it can generate output clocks at different frequencies. The Si5328 input clock frequency and clock multiplication ratio are programmable through an I²C or SPI interface. Silicon Laboratories offers a PC-based software utility, *DSPLLsim*, that can be used to determine the optimum PLL divider settings for a given input frequency/clock multiplication ratio combination that minimizes phase noise and power consumption. This utility can be downloaded from <http://www.silabs.com/timing>.

The Si5328 is based on Silicon Laboratories' 3rd-generation DSPLL[®] technology, which provides any frequency synthesis and jitter attenuation in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The Si5328 PLL loop bandwidth is digitally programmable and supports a range from less than 0.1 Hz to 6 Hz. The *DSPLLsim* software utility can be used to calculate valid loop bandwidth settings for a given input clock frequency/clock multiplication ratio.

The Si5328 supports hitless switching between the two synchronous input clocks in compliance with G.8262 that greatly minimizes the propagation of phase transients to the clock outputs during an input clock transition (maximum 200 ps phase transient). Manual and automatic revertive and non-revertive input clock switching options are available. The Si5328 monitors both input clocks for loss-of-signal (LOS) and provides a LOS alarm (INT_C1B and C2B) when it detects missing pulses on either input clock. The device monitors the lock status of the PLL. The lock detect algorithm works by continuously monitoring the phase of the input clock in relation to the phase of the feedback clock. The Si5328 also monitors frequency offset alarms (FOS), which indicate if an input clock is within a specified frequency band relative to the frequency of a reference clock. Both Stratum 3/3E and SONET Minimum Clock (SMC) FOS thresholds are supported. The Si5328 provides a digital hold capability that allows the device to continue generation of a stable output clock when the selected input reference is lost. During digital hold, the DSPLL generates an output frequency based on a historical average frequency that existed for a fixed amount of time before the error event occurred, eliminating the effects of phase and frequency transients that may occur immediately preceding digital hold.

The Si5328 has two differential clock outputs. The electrical format of each clock output is independently programmable to support LVPECL, LVDS, CML, or CMOS loads. If not required, the second clock output can be powered down to minimize power consumption.

The phase of one output clock may be adjusted in relation to the phase of the other output clock with resolution that varies from 800 ps to 2.2 ns, depending on the PLL divider settings. See Table 9 for instructions on ensuring output-to-output alignment. The input to output skew is not specified or controlled. The DSPLLsim software utility determines the phase offset resolution for a given input clock/clock multiplication ratio combination. For system-level debugging, a bypass mode is available which drives the output clock directly from the input clock, bypassing the internal DSPLL. The device is powered by a single 2.5 or 3.3 V supply.

4.1. External XAXB Reference

In order to achieve the levels of performance required by G.8262, care must be exercised when selecting an XA/XB reference. To meet the wander specifications in G.8262, a TCXO or OCXO will be needed.

“AN775: Si5328 ITU-T G.8262 SyncE Compliance Test Report” is a G.8262 test report using a 40 MHz Rakon RTX7050A-109 TCXO. See “AN776: Using the Si5328 in a G.8262 Compliant SyncE Application” for a discussion of how to select and best use a TCXO as well as a list of other potential TCXO sources.

4.2. Further Documentation

Consult the Silicon Laboratories Si53xx Any Frequency Precision Clock Family Reference Manual (FRM) for detailed information about the Si5328 functions. Additional design support is available from Silicon Laboratories through your distributor.

Silicon Laboratories has developed a PC-based software utility called DSPLLsim to simplify device configuration, including frequency planning and loop bandwidth selection. The FRM and this utility can be downloaded from <http://www.silabs.com/timing>.

Table 9. CKOUT_ALWAYS_ON and SQ_ICAL Truth Table

CKOUT_ALWAYS_ON	SQ_ICAL	Results
0	0	CKOUT OFF until after the first ICAL
0	1	CKOUT OFF until after the first successful ICAL (i.e., when LOL is low)
1	0	CKOUT always ON, including during an ICAL
1	1	CKOUT always ON, including during an ICAL. Use these settings to preserve output-to-output skew

5. Register Map

All register bits that are not defined in this map should always be written with the specified Reset Values. The writing to these bits of values other than the specified Reset Values may result in undefined device behavior. Registers not listed, such as Register 64, should never be written to.

Register	D7	D6	D5	D4	D3	D2	D1	D0
0		FREE_RUN	CKOUT_ALWAYS_ON				BYPASS_REG	
1					CK_PRIOR2[1:0]		CK_PRIOR[1:0]	
2	BWSEL_REG[3:0]							
3	CKSEL_REG[1:0]		DHOLD	SQ_ICAL				
4	AUTOSEL_REG[1:0]			HST_DEL[4:0]				
5	ICMOS[1:0]							
6		SLEEP	SFOUT2_REG[2:0]			SFOUT1_REG[2:0]		
7						FOSREFSEL[2:0]		
8	HLOG_2[1:0]		HLOG_1[1:0]					
9	HIST_AVG[4:0]							
10					DSBL2_REG	DSBL1_REG		
11							PD_CK2	PD_CK1
19	FOS_EN	FOS_THR[1:0]		VALTIME[1:0]		LOCK[T2:0]		
20					CK2_BAD_PIN	CK1_BAD_PIN	LOL_PIN	INT_PIN
21							CK1_ACTV_PIN	CKSEL_PIN
22					CK_ACTV_POL	CK_BAD_POL	LOL_POL	INT_POL
23						LOS2_MSK	LOS1_MSK	LOSX_MSK
24						FOS2_MSK	FOS1_MSK	LOL_MSK
25	N1_HS[2:0]							
31					NC1_LS[19:16]			
32	NC1_LS[15:8]							
33	NC1_LS[7:0]							
34					NC2_LS[19:16]			

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Register	D7	D6	D5	D4	D3	D2	D1	D0
35	NC2_LS[15:8]							
36	NC2_LS[7:0]							
40	N2_HS[2:0]				N2_LS[19:16]			
41	N2_LS[15:8]							
42	N2_LS[7:0]							
43						N31[18:16]		
44	N31[15:8]							
45	N31[7:0]							
46						N32[18:16]		
47	N32[15:8]							
48	N32[7:0]							
55			CLKIN2RATE[2:0]			CLKIN1RATE[2:0]		
128							CK2_ACTV_REG	CK1_ACTV_REG
129						LOS2_INT	LOS1_INT	LOSX_INT
130		DIGHOLDVALID				FOS2_INT	FOS1_INT	LOL_INT
131						LOS2_FLG	LOS1_FLG	LOSX_FLG
132					FOS2_FLG	FOS1_FLG	LOL_FLG	
134	PARTNUM_RO[11:4]							
135	PARTNUM_RO[3:0]				REVID_RO[3:0]			
136	RST_REG	ICAL					GRADE_RO[1:0]	
137								FASTLOCK
138							LOS2_EN [1:1]	LOS1_EN [1:1]
139			LOS2_EN[0:0]	LOS1_EN[0:0]			FOS2_EN	FOS1_EN
142	INDEPENDENTSKEW1[7:0]							
143	INDEPENDENTSKEW2[7:0]							

6. Register Descriptions

Register 0.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		FREE_RUN	CKOUT_ALWAYS_ON				BYPASS_REG	
Type	R	R/W	R/W	R	R	R	R/W	R

Reset value = 0001 0100

Bit	Name	Function
7	Reserved	Reserved.
6	FREE_RUN	Free Run. Internal to the device, route XA/XB to CKIN2. This allows the device to lock to its XA-XB reference. 0: Disable 1: Enable
5	CKOUT_ALWAYS_ON	CKOUT Always On. This will bypass the SQ_ICAL function. Output will be available even if SQ_ICAL is on and ICAL is not complete or successful. See Table 9 on page 20. 0: Squelch output until part is calibrated (ICAL). 1: Provide an output. Note: The frequency may be significantly off and variable until the part is calibrated.
4:2	Reserved	Reserved.
1	BYPASS_REG	Bypass Register. This bit enables or disables the PLL bypass mode. Use only when the device is in digital hold or before the first ICAL. 0: Normal operation 1: Bypass mode. Selected input clock is connected to CKOUT buffers, bypassing the PLL. Bypass mode does not support CMOS clock outputs.
0	Reserved	Reserved.

Register 1.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				CK_PRIOR2 [1:0]		CK_PRIOR1 [1:0]	
Type	R				R/W		R/W	

Reset value = 1110 0100

Bit	Name	Function
7:4	Reserved	Reserved.
3:2	CK_PRIOR2 [1:0]	CK_PRIOR 2. Selects which of the input clocks will be 2nd priority in the autoselection state machine. 00: CKIN1 is 2nd priority. 01: CKIN2 is 2nd priority. 10: Reserved 11: Reserved
1:0	CK_PRIOR1 [1:0]	CK_PRIOR 1. Selects which of the input clocks will be 1st priority in the autoselection state machine. 00: CKIN1 is 1st priority. 01: CKIN2 is 1st priority. 10: Reserved 11: Reserved

Register 2.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	BWSEL_REG [3:0]				Reserved			
Type	R/W				R			

Reset value = 0100 0010

Bit	Name	Function
7:4	BWSEL_REG [3:0]	BWSEL_REG. Selects nominal f3dB bandwidth for PLL. See DSPLLsim for settings. After BWSEL_REG is written with a new value, an ICAL is required for the change to take effect.
3:0	Reserved	Reserved.

Register 3.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	CKSEL_REG [1:0]		DHOLD	SQ_ICAL	Reserved			
Type	R/W		R/W	R/W	R			

Reset value = 0000 0101

Bit	Name	Function
7:6	CKSEL_REG [1:0]	CKSEL_REG. If the device is operating in register-based manual clock selection mode (AUTOSEL_REG = 00), and CKSEL_PIN = 0, then these bits select which input clock will be the active input clock. If CKSEL_PIN = 1 and AUTOSEL_REG = 00, the CS_CA input pin continues to control clock selection and CKSEL_REG is of no consequence. 00: CKIN_1 selected. 01: CKIN_2 selected. 10: Reserved 11: Reserved
5	DHOLD	DHOLD. Forces the part into digital hold. This bit overrides all other manual and automatic clock selection controls. 0: Normal operation. 1: Force digital hold mode. Overrides all other settings and ignores the quality of all of the input clocks.
4	SQ_ICAL	SQ_ICAL. This bit determines if the output clocks will remain enabled or be squelched (disabled) during an internal calibration. See Table 9 on page 20. 0: Output clocks enabled during ICAL. 1: Output clocks disabled during ICAL.
3:0	Reserved	Reserved.

Register 4.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	AUTOSEL_REG [1:0]		Reserved	HIST_DEL [4:0]				
Type	R/W		R	R/W				

Reset value = 0001 0010

Bit	Name	Function
7:6	AUTOSEL_REG [1:0]	AUTOSEL_REG [1:0]. Selects method of input clock selection to be used. 00: Manual (either register or pin controlled, see CKSEL_PIN) 01: Automatic Non-Revertive 10: Automatic Revertive 11: Reserved See the Si53xx Family Reference Manual for a detailed description.
5	Reserved	Reserved.
4:0	HIST_DEL [4:0]	HIST_DEL [4:0]. Selects amount of delay to be used in generating the history information used for Digital Hold. See the Si53xx Family Reference Manual for a detailed description.

Register 5.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	ICMOS [1:0]		Reserved					
Type	R/W		R					

Reset value = 1110 1101

Bit	Name	Function
7:6	ICMOS [1:0]	ICMOS [1:0]. When the output buffer is set to CMOS mode, these bits determine the output buffer drive strength. The first number below refers to 3.3 V operation; the second to 2.5 V operation. These values assume CKOUT+ is tied to CKOUT–. 00: 8 mA/5 mA 01: 16 mA/10 mA 10: 24 mA/15 mA 11: 32 mA/20 mA
5:0	Reserved	Reserved.

Register 6.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved	SLEEP	SFOUT2_REG [2:0]			SFOUT1_REG [2:0]		
Type	R	R/W	R/W			R/W		

Reset value = 0010 1101

Bit	Name	Function
7	Reserved	Reserved.
6	SLEEP	SLEEP. In sleep mode, all clock outputs are disabled and the maximum amount of internal circuitry is powered down to reduce power dissipation and noise generation. This bit overrides the SFOUTn_REG[2:0] output signal format settings. 0: Normal operation 1: Sleep mode
5:3	SFOUT2_REG [2:0]	SFOUT2_REG [2:0]. Controls output signal format and disable for CKOUT2 output buffer. 000: Reserved 001: Disable 010: CMOS (Bypass mode not supported) 011: Low swing LVDS 100: Reserved 101: LVPECL 110: CML 111: LVDS
2:0	SFOUT1_REG [2:0]	SFOUT1_REG [2:0]. Controls output signal format and disable for CKOUT1 output buffer. 000: Reserved 001: Disable 010: CMOS (Bypass mode not supported) 011: Low swing LVDS 100: Reserved 101: LVPECL 111: LVDS

Register 7.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					FOSREFSEL [2:0]		
Type	R					R/W		

Reset value = 0010 1010

Bit	Name	Function
7:3	Reserved.	Reserved.
2:0	FOSREFSEL [2:0]	FOSREFSEL [2:0]. Selects which input clock is used as the reference frequency for frequency offset (FOS) alarms. 000: XA/XB (External reference) 001: CKIN1 010: CKIN2 011: Reserved 100: Reserved 101: Reserved 110: Reserved 111: Reserved

Register 8.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	HLOG_2[1:0]		HLOG_1[1:0]		Reserved			
Type	R/W		R/W		R			

Reset value = 0000 0000

Bit	Name	Function
7:6	HLOG_2 [1:0]	HLOG_2 [1:0]. 00: Normal operation 01: Holds CKOUT2 output at static logic 0. Entrance and exit from this state will occur without glitches or runt pulses. 10: Holds CKOUT2 output at static logic 1. Entrance and exit from this state will occur without glitches or runt pulses. 11: Reserved
5:4		HLOG_1 [1:0]. 00: Normal operation 01: Holds CKOUT1 output at static logic 0. Entrance and exit from this state will occur without glitches or runt pulses. 10: Holds CKOUT1 output at static logic 1. Entrance and exit from this state will occur without glitches or runt pulses. 11: Reserved
3:0	Reserved	Reserved.

Register 9.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	HIST_AVG [4:0]					Reserved		
Type	R/W					R	R	R

Reset value = 1100 0000

Bit	Name	Function
7:3	HIST_AVG [4:0]	HIST_AVG [4:0]. Selects amount of averaging time to be used in generating the history information for Digital Hold. See the Si53xx Family Reference Manual for a detailed description
2:0	Reserved	Reserved.

Register 10.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				DSBL2_REG	DSBL1_REG	Reserved	Reserved
Type	R				R/W	R/W	R	R

Reset value = 0000 0000

Bit	Name	Function
7:4	Reserved	Reserved.
3	DSBL2_REG	DSBL2_REG. This bit controls the powerdown of the CKOUT2 output buffer. If disable mode is selected, the N2_LS output divider is also powered down. 0: CKOUT2 enabled 1: CKOUT2 disabled
2	DSBL1_REG	DSBL1_REG. This bit controls the powerdown of the CKOUT1 output buffer. If disable mode is selected, the N1_LS output divider is also powered down. 0: CKOUT1 enabled 1: CKOUT1 disabled
1:0	Reserved	Reserved.

Register 11.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved						PD_CK2	PD_CK1
Type	R						R/W	R/W

Reset value = 0100 0000

Bit	Name	Function
7:2	Reserved	Reserved.
1	PD_CK2	PD_CK2. This bit controls the powerdown of the CKIN2 input buffer. 0: CKIN2 enabled 1: CKIN2 disabled
0	PD_CK1	PD_CK1. This bit controls the powerdown of the CKIN1 input buffer. 0: CKIN1 enabled 1: CKIN1 disabled

Register 19.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	FOS_EN	FOS_THR [1:0]		VALTIME [1:0]		LOCKT [2:0]		
Type	R/W	R/W		R/W		R/W		

Reset value = 0010 1100

Bit	Name	Function
7	FOS_EN	FOS_EN. Frequency Offset Enable globally disables FOS. See the individual FOS enables (FOSX_EN, register 139). 0: FOS disable 1: FOS enabled by FOSx_EN
6:5	FOS_THR [1:0]	FOS_THR [1:0]. Frequency Offset at which FOS is declared (relative to the selected FOS reference): 00: ± 11 to 12 ppm (Stratum 3/3E compliant, with a Stratum 3/3E used for REFCLK) 01: ± 48 to 49 ppm (SMC) 10: ± 30 ppm (SONET Minimum Clock (SMC), with a Stratum 3/3E used for REFCLK. 11: ± 200 ppm
4:3	VALTIME [1:0]	VALTIME [1:0]. Sets amount of time for input clock to be valid before the associated alarm is removed. 00: 2 ms 01: 100 ms 10: 200 ms 11: 13 seconds
2:0	LOCKT [2:0]	LOCKT [2:0]. Sets retrigger interval for one shot monitoring phase detector output. One shot is triggered by phase slip in DSPLL. Refer to the Si53xx Family Reference Manual for more details. 000: 106 ms 001: 53 ms 010: 26.5 ms 011: 13.3 ms 100: 6.6 ms 101: 3.3 ms 110: 1.66 ms 111: .833 ms

Register 20.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				CK2_BAD_PIN	CK1_BAD_PIN	LOL_PIN	INT_PIN
Type	R				R/W	R/W	R/W	R/W

Reset value = 0011 1110

Bit	Name	Function
7:4	Reserved	Reserved.
3	CK2_BAD_PIN	CK2_BAD_PIN. The CK2_BAD status can be reflected on the C2B output pin. 0: C2B output pin tristated 1: C2B status reflected to output pin
2	CK1_BAD_PIN	CK1_BAD_PIN. Either LOS1 or INT (see INT_PIN) status can be reflected on the INT_C1B output pin. 0: INT_C1B output pin tristated 1: LOS1 or INT (see INT_PIN) status reflected to output pin
1	LOL_PIN	LOL_PIN. The LOL_INT status bit can be reflected on the LOL output pin. 0: LOL output pin tristated 1: LOL_INT status reflected to output pin
0	INT_PIN	INT_PIN. Reflects the interrupt status on the INT_C1B output pin. 0: Interrupt status not displayed on INT_C1B output pin. Instead, the INT_C1B pin indicates when CKIN1 is bad. If CK1_BAD_PIN = 0, INT_C1B output pin is tristated. 1: Interrupt status reflected to output pin.

Register 21.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved	Reserved					CK1_ACTV_PIN	CKSEL_PIN
Type	R	Force 1	R	R	R	R	R/W	R/W

Reset value = 1111 1111

Bit	Name	Function
7:2	Reserved	Reserved.
1	CK1_ACTV_PIN	CK1_ACTV_PIN. The CK1_ACTV_REG status bit can be reflected to the CS_CA output pin using the CK1_ACTV_PIN enable function. CK1_ACTV_PIN is of consequence only when pin controlled clock selection is not being used. (See CKSEL_PIN) 0: CS_CA output pin tristated. 1: Clock Active status reflected to output pin.
0	CKSEL_PIN	CKSEL_PIN. If manual clock selection is being used, clock selection can be controlled via the CKSEL_REG[1:0] register bits or the CS_CA input pin. This bit is only active when AUTOSEL_REG = Manual. 0: CS_CA pin is ignored. CKSEL_REG[1:0] register bits control clock selection. 1: CS_CA input pin controls clock selection.

Register 22.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				CK_ACTV_POL	CK_BAD_POL	LOL_POL	INT_POL
Type	R				R/W	R/W	R/W	R/W

Reset value = 1101 1111

Bit	Name	Function
7:4	Reserved	Reserved.
3	CK_ACTV_POL	CK_ACTV_POL. Sets the active polarity for the CS_CA signals when reflected on an output pin. 0: Active low 1: Active high
2	CK_BAD_POL	CK_BAD_POL. Sets the active polarity for the INT_C1B and C2B signals when reflected on output pins. 0: Active low 1: Active high
1	LOL_POL	LOL_POL. Sets the active polarity for the LOL status when reflected on an output pin. 0: Active low 1: Active high
0	INT_POL	INT_POL. Sets the active polarity for the interrupt status when reflected on the INT_C1B output pin. 0: Active low 1: Active high

Register 23.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					LOS2_MSK	LOS1_MSK	LOSX_MSK
Type	R					R/W	R/W	R/W

Reset value = 0001 1111

Bit	Name	Function
7:3	Reserved	Reserved.
2	LOS2_MSK	LOS2_MSK. Determines if a LOS on CKIN2 (LOS2_FLG) is used in the generation of an interrupt. Writes to this register do not change the value held in the LOS2_FLG register. 0: LOS2 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: LOS2_FLG ignored in generating interrupt output.
1	LOS1_MSK	LOS1_MSK. Determines if a LOS on CKIN1 (LOS1_FLG) is used in the generation of an interrupt. Writes to this register do not change the value held in the LOS1_FLG register. 0: LOS1 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: LOS1_FLG ignored in generating interrupt output.
0	LOSX_MSK	LOSX_MSK. Determines if a LOS on XA/XB(LOSX_FLG) is used in the generation of an interrupt. Writes to this register do not change the value held in the LOSX_FLG register. 0: LOSX alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: LOSX_FLG ignored in generating interrupt output.

Register 24.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					FOS2_MSK	FOS1_MSK	LOL_MSK
Type	R					R/W	R/W	R/W

Reset value = 0011 1111

Bit	Name	Function
7:3	Reserved	Reserved.
2	FOS2_MSK	FOS2_MSK. Determines if the FOS2_FLG is used in the generation of an interrupt. Writes to this register do not change the value held in the FOS2_FLG register. 0: FOS2 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: FOS2_FLG ignored in generating interrupt output.
1	FOS1_MSK	FOS1_MSK. Determines if the FOS1_FLG is used in the generation of an interrupt. Writes to this register do not change the value held in the FOS1_FLG register. 0: FOS1 alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: FOS1_FLG ignored in generating interrupt output.
0	LOL_MSK	LOL_MSK. Determines if the LOL_FLG is used in the generation of an interrupt. Writes to this register do not change the value held in the LOL_FLG register. 0: LOL alarm triggers active interrupt on INT_C1B output (if INT_PIN=1). 1: LOL_FLG ignored in generating interrupt output.

Register 25.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N1_HS [2:0]			Reserved				
Type	R/W			R				

Reset value = 0010 0000

Bit	Name	Function
7:5	N1_HS [2:0]	N1_HS [2:0]. Sets value for N1 high speed divider which drives NCn_LS (n = 1 to 2) low-speed divider. 000: N1 = 4 001: N1 = 5 010: N1 = 6 011: N1 = 7 100: N1 = 8 101: N1 = 9 110: N1 = 10 111: N1 = 11
4:0	Reserved	Reserved.

Register 31.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				NC1_LS [19:16]			
Type	R				R/W			

Reset value = 0000 0000

Bit	Name	Function
7:4	Reserved	Reserved.
3:0	NC1_LS [19:16]	NC1_LS [19:16]. Sets value for NC1 low-speed divider, which drives CKOUT1 output. Must be 0 or odd. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [1, 2, 4, 6, ..., 2^{20}]

Register 32.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	NC1_LS [15:8]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	NC1_LS [15:8]	NC1_LS [15:8]. Sets value for NC1 low-speed divider, which drives CKOUT1 output. Must be 0 or odd. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [1, 2, 4, 6, ..., 2^{20}]

Register 33.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	NC1_LS [7:0]							
Type	R/W							

Reset value = 0011 0001

Bit	Name	Function
7:0	NC1_LS [19:0]	NC1_LS [7:0]. Sets value for N1 low-speed divider, which drives CKOUT1 output. Must be 0 or odd. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [1, 2, 4, 6, ..., 2^{20}]

Register 34.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				NC2_LS [19:16]			
Type	R				R/W			

Reset value = 0000 0000

Bit	Name	Function
7:4	Reserved	Reserved.
3:0	NC2_LS [19:16]	NC2_LS [19:16]. Sets value for NC2 low-speed divider, which drives CKOUT2 output. Must be 0 or odd. 00000000000000000000=1 00000000000000000001=2 00000000000000000011=4 00000000000000000101=6 ... 11111111111111111111=2 ²⁰ Valid divider values=[1, 2, 4, 6, ..., 2 ²⁰]

Register 35.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	NC2_LS [15:8]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	NC2_LS [15:8]	NC2_LS [15:8]. Sets value for NC2 low-speed divider, which drives CKOUT2 output. Must be 0 or odd. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111=2 ²⁰ Valid divider values=[1, 2, 4, 6, ..., 2 ²⁰]

Register 36.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	NC2_LS [7:0]							
Type	R/W							

Reset value = 0011 0001

Bit	Name	Function
7:0	NC2_LS [7:0]	NC2_LS [7:0]. Sets value for NC2 low-speed divider, which drives CKOUT2 output. Must be 0 or odd. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [1, 2, 4, 6, ..., 2^{20}]

Register 40.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N2_HS [2:0]			Reserved	N2_LS [19:16]			
Type	R/W			R	R/W			

Reset value = 1100 0000

Bit	Name	Function
7:5	N2_HS [2:0]	N2_HS [2:0]. Sets value for N2 high speed divider, which drives N2LS low-speed divider. 000: 4 001: 5 010: 6 011: 7 100: 8 101: 9 110: 10 111: 11
4	Reserved	Reserved.
3:0	N2_LS [19:16]	N2_LS [19:16]. Sets value for N2 low-speed divider, which drives phase detector. 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [2, 4, 6, ..., 2^{20}]

Register 41.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N2_LS [15:8]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	N2_LS [15:8]	N2_LS [15:8]. Sets value for N2 low-speed divider, which drives phase detector. 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [2, 4, 6, ..., 2^{20}]

Register 42.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N2_LS [7:0]							
Type	R/W							

Reset value = 1111 1001

Bit	Name	Function
7:0	N2_LS [7:0]	N2_LS [7:0]. Sets value for N2 low-speed divider, which drives phase detector. 00000000000000000001 = 2 00000000000000000011 = 4 00000000000000000101 = 6 ... 11111111111111111111 = 2^{20} Valid divider values = [2, 4, 6, ..., 2^{20}]

Register 43.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					N31 [18:16]		
Type	R					R/W		

Reset value = 0000 0000

Bit	Name	Function
7:3	Reserved	Reserved.
2:0	N31 [18:16]	N31 [18:16]. Sets value for input divider for CKIN1. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000010 = 3 ... 11111111111111111111 = 2^{19} Valid divider values=[1, 2, 3, ..., 2^{19}]

Register 44.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N31_[15:8]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	N31_[15:8]	N31_[15:8]. Sets value for input divider for CKIN1. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000010 = 3 ... 11111111111111111111 = 2^{19} Valid divider values=[1, 2, 3, ..., 2^{19}]

Register 45.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N31_[7:0]							
Type	R/W							

Reset value = 0000 1001

Bit	Name	Function
7:0	N31_[7:0]	N31_[7:0]. Sets value for input divider for CKIN1. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000010 = 3 ... 11111111111111111111 = 2^{19} Valid divider values=[1, 2, 3, ..., 2^{19}]

Register 46.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					N32_[18:16]		
Type	R					R/W		

Reset value = 0000 0000

Bit	Name	Function
7:3	Reserved	Reserved.
2:0	N32_[18:16]	N32_[18:16]. Sets value for input divider for CKIN2. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000010 = 3 ... 11111111111111111111 = 2^{19} Valid divider values=[1, 2, 3, ..., 2^{19}]

Register 47.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N32_[15:8]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	N32_[15:8]	N32_[15:8]. Sets value for input divider for CKIN2. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000010 = 3 ... 11111111111111111111 = 2^{19} Valid divider values=[1, 2, 3, ..., 2^{19}]

Register 48.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	N32_[7:0]							
Type	R/W							

Reset value = 0000 1001

Bit	Name	Function
7:0	N32_[7:0]	N32_[7:0]. Sets value for input divider for CKIN1. 00000000000000000000 = 1 00000000000000000001 = 2 00000000000000000010 = 3 ... 11111111111111111111 = 2^{19} Valid divider values=[1, 2, 3, ..., 2^{19}]

Register 55.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved		CLKIN2RATE_[2:0]			CLKIN1RATE[2:0]		
Type	R		R/W			R/W		

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	Reserved.
5:3	CLKIN2RATE[2:0]	CLKIN2RATE[2:0]. CKINn frequency selection for FOS alarm monitoring. 000: 10–27 MHz 001: 25–54 MHz 010: 50–105 MHz 011: 95–215 MHz 100: 190–435 MHz 101: 375–710 MHz 110: Reserved 111: Reserved
2:0	CLKIN1RATE [2:0]	CLKIN1RATE[2:0]. CKINn frequency selection for FOS alarm monitoring. 000: 10–27 MHz 001: 25–54 MHz 010: 50–105 MHz 011: 95–215 MHz 100: 190–435 MHz 101: 375–710 MHz 110: Reserved 111: Reserved

Register 128.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved						CK2_ACTV_REG	CK1_ACTV_REG
Type	R						R	R

Reset value = 0010 0000

Bit	Name	Function
7:2	Reserved	Reserved.
1	CK2_ACTV_REG	CK2_ACTV_REG. Indicates if CKIN2 is currently the active clock for the PLL input. 0: CKIN2 is not the active input clock. Either it is not selected or LOS2_INT is 1. 1: CKIN2 is the active input clock.
0	CK1_ACTV_REG	CK1_ACTV_REG. Indicates if CKIN1 is currently the active clock for the PLL input. 0: CKIN1 is not the active input clock. Either it is not selected or LOS1_INT is 1. 1: CKIN1 is the active input clock.

Register 129.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					LOS2_INT	LOS1_INT	LOSX_INT
Type	R					R	R	R

Reset value = 0000 0110

Bit	Name	Function
7:3	Reserved	Reserved.
2	LOS2_INT	LOS2_INT. Indicates the LOS status on CKIN2. 0: Normal operation. 1: Internal loss-of-signal alarm on CKIN2 input.
1	LOS1_INT	LOS1_INT. Indicates the LOS status on CKIN1. 0: Normal operation. 1: Internal loss-of-signal alarm on CKIN1 input.
0	LOSX_INT	LOSX_INT. Indicates the LOS status of the external reference on the XA/XB pins. 0: Normal operation. 1: Internal loss-of-signal alarm on XA/XB reference clock input.

Register 130.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved	DIGHOLDVALID	Reserved			FOS2_INT	FOS1_INT	LOL_INT
Type	R	R	R			R	R	R

Reset value = 0000 0001

Bit	Name	Function
7	Reserved	Reserved.
6	DIGHOLDVALID	Digital Hold Valid. Indicates if the digital hold circuit has enough samples of a valid clock to meet digital hold specifications. 0: Indicates digital hold history registers have not been filled. The digital hold output frequency may not meet specifications. 1: Indicates digital hold history registers have been filled. The digital hold output frequency is valid.
5:3	Reserved	Reserved.
2	FOS2_INT	CKIN2 Frequency Offset Status. 0: Normal operation. 1: Internal frequency offset alarm on CKIN2 input.
1	FOS1_INT	CKIN1 Frequency Offset Status. 0: Normal operation. 1: Internal frequency offset alarm on CKIN1 input.
0	LOL_INT	PLL Loss of Lock Status. 0: PLL locked. 1: PLL unlocked.

Register 131.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved					LOS2_FLG	LOS1_FLG	LOSX_FLG
Type	R					R/W	R/W	R/W

Reset value = 0001 1111

Bit	Name	Function
7:3	Reserved	Reserved.
2	LOS2_FLG	CKIN2 Loss-of-Signal Flag. 0: Normal operation. 1: Held version of LOS2_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOS2_MSK bit. Flag cleared by writing 0 to this bit.
1	LOS1_FLG	CKIN1 Loss-of-Signal Flag. 0: Normal operation 1: Held version of LOS1_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOS1_MSK bit. Flag cleared by writing 0 to this bit.
0	LOSX_FLG	External Reference (signal on pins XA/XB) Loss-of-Signal Flag. 0: Normal operation 1: Held version of LOSX_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOSX_MSK bit. Flag cleared by writing 0 to this bit.

Register 132.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved				FOS2_FLG	FOS1_FLG	LOL_FLG	Reserved
Type	R				R/W	R/W	R/W	R

Reset value = 0000 0010

Bit	Name	Function
7:4	Reserved	Reserved.
3	FOS2_FLG	CLKIN_2 Frequency Offset Flag. 0: Normal operation. 1: Held version of FOS2_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by FOS2_MSK bit. Flag cleared by writing 0 to this bit.
2	FOS1_FLG	CLKIN_1 Frequency Offset Flag. 0: Normal operation 1: Held version of FOS1_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by FOS1_MSK bit. Flag cleared by writing 0 to this bit.
1	LOL_FLG	PLL Loss of Lock Flag. 0: PLL locked 1: Held version of LOL_INT. Generates active output interrupt if output interrupt pin is enabled (INT_PIN = 1) and if not masked by LOL_MSK bit. Flag cleared by writing 0 to this bit.
0	Reserved	Reserved.

Register 134.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	PARTNUM_RO [11:4]							
Type	R							

Reset value = 0000 0001

Bit	Name	Function
7:0	PARTNUM_RO [11:0]	Device ID (1 of 2). 0000 0001 1100: Si5328

Register 135.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	PARTNUM_RO [3:0]				REVID_RO [3:0]			
Type	R				R			

Reset value = 1100 0010

Bit	Name	Function
7:4	PARTNUM_RO [11:0]	Device ID (2 of 2). 0000 0001 1100: Si5328
3:0	REVID_RO [3:0]	Device Revision. 0010: Revision C Others: Reserved

Register 136.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	RST_REG	ICAL	Reserved					
Type	R/W	R/W	R					

Reset value = 0000 0000

Bit	Name	Function
7	RST_REG	Internal Reset (Same as Pin Reset). Note: The I ² C (or SPI) port may not be accessed until 10 ms after RST_REG is asserted. 0: Normal operation. 1: Reset of all internal logic. Outputs disabled or tristated during reset.
6	ICAL	Start an Internal Calibration Sequence. For proper operation, the device must go through an internal calibration sequence. ICAL is a self-clearing bit. Writing a "1" to this location initiates an ICAL. The calibration is complete once the LOL alarm goes low. 0: Normal operation. 1: Writing a "1" initiates internal self-calibration. Upon completion of internal self-calibration, LOL will go low. Notes: 1. A valid stable clock (within 100 ppm) must be present to begin ICAL. 2. If the input changes by more than 500 ppm, the part may do an autonomous ICAL. 3. See Table 10, "Register Locations Requiring ICAL," on page 62 for register changes that require an ICAL.
5:0	Reserved	Reserved.

Register 137.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name								FASTLOCK
Type	R	R	R	R	R	R	R	R/W

Reset value = 0000 0000

Bit	Name	Function
7:1	Reserved	Do not modify.
0	FASTLOCK	This bit must be set to 1 to enable FASTLOCK. This improves initial lock time by dynamically changing the loop bandwidth.

Register 138.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved						LOS2_EN[1:1]	LOS1_EN [1:1]
Type	R						R/W	R/W

Reset value = 0000 1111

Bit	Name	Function
7:2	Reserved	Reserved.
1	LOS2_EN [1:0]	Enable CKIN2 LOS Monitoring on the Specified Input (2 of 2). Note: LOS2_EN is split between two registers. 00: Disable LOS monitoring 01: Reserved 10: Enable LOSA monitoring 11: Enable LOS monitoring LOSA is a slower and less sensitive version of LOS. SEe the Si53xx Family Reference Manual for details.
0	LOS1_EN [1:0]	Enable CKIN1 LOS Monitoring on the Specified Input (1 of 2). Note: LOS1_EN is split between two registers. 00: Disable LOS monitoring 01: Reserved 10: Enable LOSA monitoring 11: Enable LOS monitoring LOSA is a slower and less sensitive version of LOS. See the Si53xx Family Reference Manual for details.

Register 139.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	Reserved		LOS2_EN [0:0]	LOS1_EN [0:0]	Reserved		FOS2_EN	FOS1_EN
Type	R		R/W	R/W	R		R/W	R/W

Reset value = 1111 1111

Bit	Name	Function
7:6	Reserved	Reserved.
5	LOS2_EN [1:0]	Enable CKIN2 LOS Monitoring on the Specified Input (2 of 2). Note: LOS2_EN is split between two registers. 00: Disable LOS monitoring 01: Reserved 10: Enable LOSA monitoring 11: Enable LOS monitoring LOSA is a slower and less sensitive version of LOS. See the Si53xx Family Reference Manual for details
4	LOS1_EN [1:0]	Enable CKIN1 LOS Monitoring on the Specified Input (1 of 2). Note: LOS1_EN is split between two registers. 00: Disable LOS monitoring 01: Reserved 10: Enable LOSA monitoring 11: Enable LOS monitoring LOSA is a slower and less sensitive version of LOS. See the Si53xx Family Reference Manual for details.
3:2	Reserved	Reserved.
1	FOS2_EN	Enables FOS on a Per Channel Basis. 0: Disable FOS monitoring 1: Enable FOS monitoring
0	FOS1_EN	Enables FOS on a Per Channel Basis. 0: Disable FOS monitoring 1: Enable FOS monitoring

Register 142.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	INDEPENDENTSKEW1 [7:0]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	INDEPEND-ENTSKEW1 [7:0]	INDEPENDENTSKEW1. Eight-bit field that represents a 2's complement of the phase offset in terms of clocks from the high speed output divider.

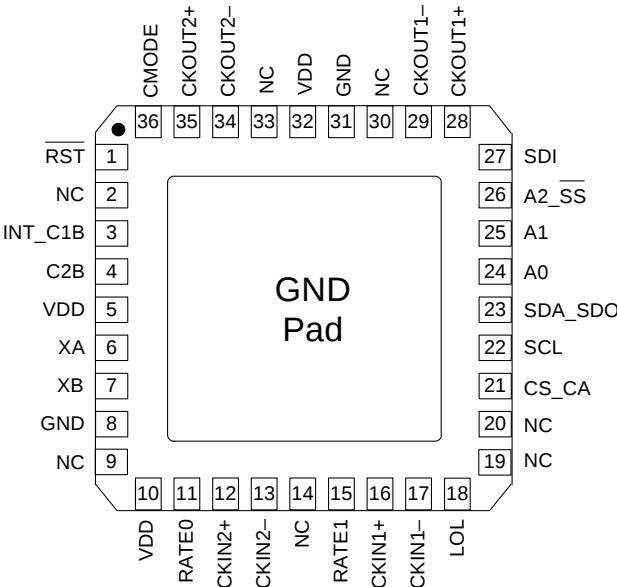
Register 143.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	INDEPENDENTSKEW2 [7:0]							
Type	R/W							

Reset value = 0000 0000

Bit	Name	Function
7:0	INDEPEND-ENTSKEW2 [7:0]	INDEPENDENTSKEW2. Eight-bit field that represents a 2's complement of the phase offset in terms of clocks from the high speed output divider.

7. Pin Descriptions: Si5328



Pin #	Pin Name	I/O	Signal Level	Description
1	$\overline{\text{RST}}$	I	LVC MOS	External Reset. Active low input that performs external hardware reset of device. Resets all internal logic to a known state and forces the device registers to their default value. Clock outputs are tristated during reset. The part must be programmed after a reset or power on to get a clock output. See the Si53xx Family Reference Manual for details. This pin has a weak pull-up.
2, 9, 14, 19, 20, 30, 33	NC	—	—	No Connection. Leave floating. Make no external connections to this pin for normal operation.
3	INT_C1B	O	LVC MOS	Interrupt/CKIN1 Invalid Indicator. This pin functions as a device interrupt output or an alarm output for CKIN1. If used as an interrupt output, <i>INT_PIN</i> must be set to 1. The pin functions as a maskable interrupt output with active polarity controlled by the <i>INT_POL</i> register bit. If used as an alarm output, the pin functions as a LOS (and optionally FOS) alarm indicator for CKIN1. Set <i>CK1_BAD_PIN</i> = 1 and <i>INT_PIN</i> = 0. 0 = CKIN1 present 1 = LOS (FOS) on CKIN1 The active polarity is controlled by <i>CK_BAD_POL</i> . If no function is selected, the pin tristates.

Note: Internal register names are indicated by underlined italics, e.g., *INT_PIN*. See Section "5.Register Map".

Pin #	Pin Name	I/O	Signal Level	Description
4	C2B	O	LVC MOS	CKIN2 Invalid Indicator. This pin functions as a LOS (and optionally FOS) alarm indicator for CKIN2 if <i>CK2_BAD_PIN</i> = 1. 0 = CKIN2 present 1 = LOS (FOS) on CKIN2 The active polarity can be changed by <i>CK_BAD_POL</i> . If <i>CK2_BAD_PIN</i> = 0, the pin tristates.
5, 10, 32	V _{DD}	V _{DD}	Supply	Supply. The device operates from a 2.5 or 3.3 V supply. Bypass capacitors should be associated with the following V _{DD} pins: 5 0.1 µF 10 0.1 µF 32 0.1 µF A 1.0 µF should also be placed as close to the device as is practical.
7 6	XB XA	I	Analog	Reference Clock. A TCXO or OCXO should be connected to these pins. Refer to the Si53xx Family Reference Manual for interfacing to the external reference. External reference must be from a high-quality clock source (TCXO, OCXO). Frequency of crystal or external clock is set by RATE[1:0] pins.
8, 31	GND	GND	Supply	Ground. Must be connected to system ground. Minimize the ground path impedance for optimal performance of this device. Grounding these pins does not eliminate the requirement to ground the GND PAD on the bottom of the package.
11 15	RATE0 RATE1	I	3-Level	Reference Clock Rate. Three level inputs that select the type and rate of external crystal or reference clock to be applied to the XA/XB port. Refer to the Si53xx Family Reference Manual for settings. These pins have both a weak pull-up and a weak pull-down; they default to M. L setting corresponds to ground. M setting corresponds to V _{DD} /2. H setting corresponds to V _{DD} . Some designs may require an external resistor voltage divider when driven by an active device that will tristate.
16 17	CKIN1+ CKIN1–	I	Multi	Clock Input 1. Differential input clock. This input can also be driven with a single-ended signal.
12 13	CKIN2+ CKIN2–	I	Multi	Clock Input 2. Differential input clock. This input can also be driven with a single-ended signal.
Note: Internal register names are indicated by underlined italics, e.g., <i>INT_PIN</i> . See Section “5.Register Map”.				

Pin #	Pin Name	I/O	Signal Level	Description
18	LOL	O	LVC MOS	PLL Loss of Lock Indicator. This pin functions as the active high PLL loss of lock indicator if the <u>LOL_PIN</u> register bit is set to 1. 0 = PLL locked 1 = PLL unlocked If <u>LOL_PIN</u> = 0, this pin will tristate. Active polarity is controlled by the <u>LOL_POL</u> bit. The PLL lock status will always be reflected in the <u>LOL_INT</u> read only register bit.
21	CS_CA	I/O	LVC MOS	Input Clock Select/Active Clock Indicator. Input: In manual clock selection mode, this pin functions as the manual input clock selector if the <u>CKSEL_PIN</u> is set to 1. 0 = Select CKIN1 1 = Select CKIN2 If <u>CKSEL_PIN</u> = 0, the <u>CKSEL_REG</u> register bit controls this function and this input tristates. If configured for input, must be tied high or low. Output: In automatic clock selection mode, this pin indicates which of the two input clocks is currently the active clock. If alarms exist on both clocks, CK_ACTV will indicate the last active clock that was used before entering the digital hold state. The <u>CK_ACTV_PIN</u> register bit must be set to 1 to reflect the active clock status to the CK_ACTV output pin. 0 = CKIN1 active input clock 1 = CKIN2 active input clock If <u>CK_ACTV_PIN</u> = 0, this pin will tristate. The CK_ACTV status will always be reflected in the <u>CK_ACTV_REG</u> read only register bit.
22	SCL	I	LVC MOS	Serial Clock. This pin functions as the serial clock input for both SPI and I ² C modes. This pin has a weak pull-down.
23	SDA_SDO	I/O	LVC MOS	Serial Data. In I ² C control mode (CMODE = 0), this pin functions as the bidirectional serial data port. In SPI control mode (CMODE = 1), this pin functions as the serial data output.
25 24	A1 A0	I	LVC MOS	Serial Port Address. In I ² C control mode (CMODE = 0), these pins function as hardware controlled address bits. The I ² C address is 1101 [A2] [A1] [A0]. In SPI control mode (CMODE = 1), these pins are ignored. These pins have a weak pull-down.
Note: Internal register names are indicated by underlined italics, e.g., <u>INT_PIN</u> . See Section "5.Register Map".				

Pin #	Pin Name	I/O	Signal Level	Description
26	A2_SS	I	LVC MOS	Serial Port Address/Slave Select. In I ² C control mode (CMODE = 0), this pin functions as a hardware controlled address bit [A2]. In SPI control mode (CMODE = 1), this pin functions as the slave select input. This pin has a weak pull-down.
27	SDI	I	LVC MOS	Serial Data In. In I ² C control mode (CMODE = 0), this pin is ignored. In SPI control mode (CMODE = 1), this pin functions as the serial data input. This pin has a weak pull-down.
29 28	CKOUT1– CKOUT1+	O	Multi	Output Clock 1. Differential output clock with a frequency range of 8 kHz to 808 MHz. Output signal format is selected by <i>SFOUT1_REG</i> register bits. Output is differential for LVPECL, LVDS, and CML compatible modes. For CMOS format, both output pins drive identical single-ended clock outputs.
34 35	CKOUT2– CKOUT2+	O	Multi	Output Clock 2. Differential output clock with a frequency range of 8 kHz to 808 MHz. Output signal format is selected by <i>SFOUT2_REG</i> register bits. Output is differential for LVPECL, LVDS, and CML compatible modes. For CMOS format, both output pins drive identical single-ended clock outputs.
36	CMODE	I	LVC MOS	Control Mode. Selects I ² C or SPI control mode. 0 = I ² C Control Mode 1 = SPI Control Mode This pin must not be NC. Tie either high or low. See the Si53xx Family Reference Manual for details on I ² C or SPI operation.
GND PAD	GND	GND	Supply	Ground Pad. The ground pad must provide a low thermal and electrical impedance to a ground plane.
Note: Internal register names are indicated by underlined italics, e.g., <i>INT_PIN</i> . See Section “5.Register Map”.				

Table 10 lists all of the register locations that should be followed by an ICAL after their contents are changed.

Table 10. Register Locations Requiring ICAL

Addr	Register
0	BYPASS_REG
0	CKOUT_ALWAYS_ON
1	CK_PRIOR2
1	CK_PRIOR1
2	BWSEL_REG
4	HIST_DEL
5	ICMOS
7	FOSREFSEL
9	HIST_AVG
10	DSBL2_REG
10	DSBL1_REG
11	PD_CK2
11	PD_CK1
19	FOS_EN
19	FOS_THR
19	VALTIME
19	LOCKT
25	N1_HS
31	NC1_LS
34	NC2_LS
40	N2_HS
40	N2_LS
43	N31
46	N32
55	CLKIN2RATE
55	CLKIN1RATE

Table 11. Si5328 Pull up/Pull down

Pin #	Si5328	Pull up/Pull down
1	RST	U
11	RATE0	U, D
15	RATE1	U, D
21	CS_CA	U, D
22	SCL	D
24	A0	D
25	A1	D
26	A2_SS	D
27	SDI	D
36	CMODE	U, D

8. Ordering Guide

Ordering Part Number	Output Clock Frequency Range	Package	ROHS6, Pb-Free	Temperature Range
Si5328B-C-GM	8 kHz–808 MHz	36-Lead 6 x 6 mm QFN	Yes	–40 to 85 °C
Si5328C-C-GM	8 kHz–346 MHz	36-Lead 6 x 6 mm QFN	Yes	–40 to 85 °C
Si5328-EVB	8 kHz–808 MHz	Evaluation Board	—	–40 to 85 °C

Note: Add an R at the end of the device to denote tape and reel options.

9. Package Outline: 36-Pin QFN

Figure 7 illustrates the package details for the Si5328. Table 12 lists the values for the dimensions shown in the illustration.

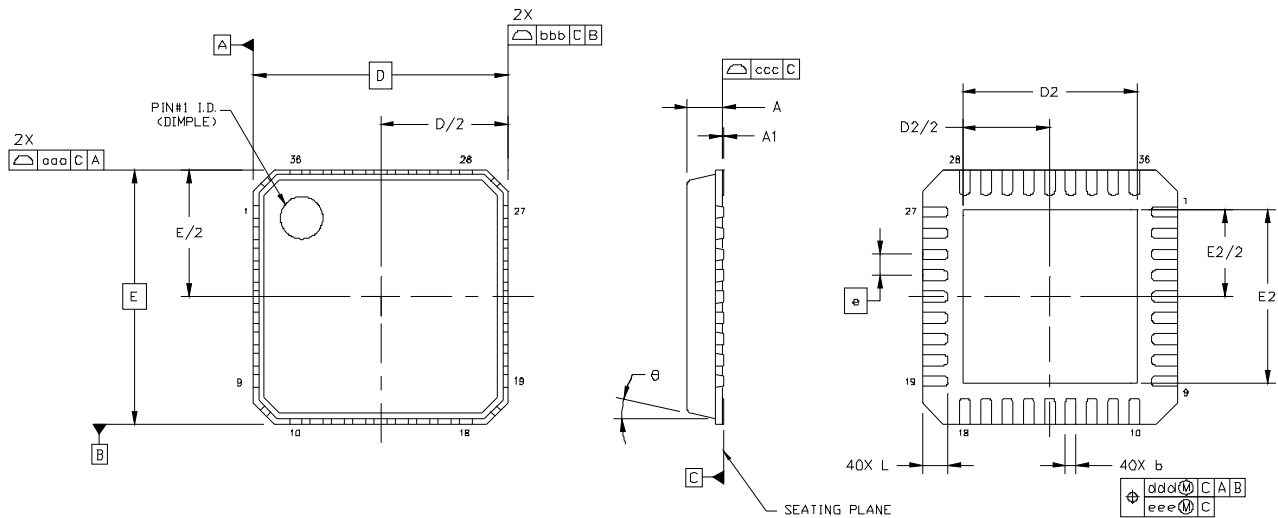


Figure 7. 36-Pin Quad Flat No-lead (QFN)

Table 12. Package Dimensions

Symbol	Millimeters		
	Min	Nom	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
b	0.18	0.25	0.30
D	6.00 BSC		
D2	3.95	4.10	4.25
e	0.50 BSC		
E	6.00 BSC		
E2	3.95	4.10	4.25

Symbol	Millimeters		
	Min	Nom	Max
L	0.50	0.60	0.70
θ	—	—	12°
aaa	—	—	0.10
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.10
eee	—	—	0.05

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to JEDEC outline MO-220, variation VJJD.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

10. Recommended PCB Layout

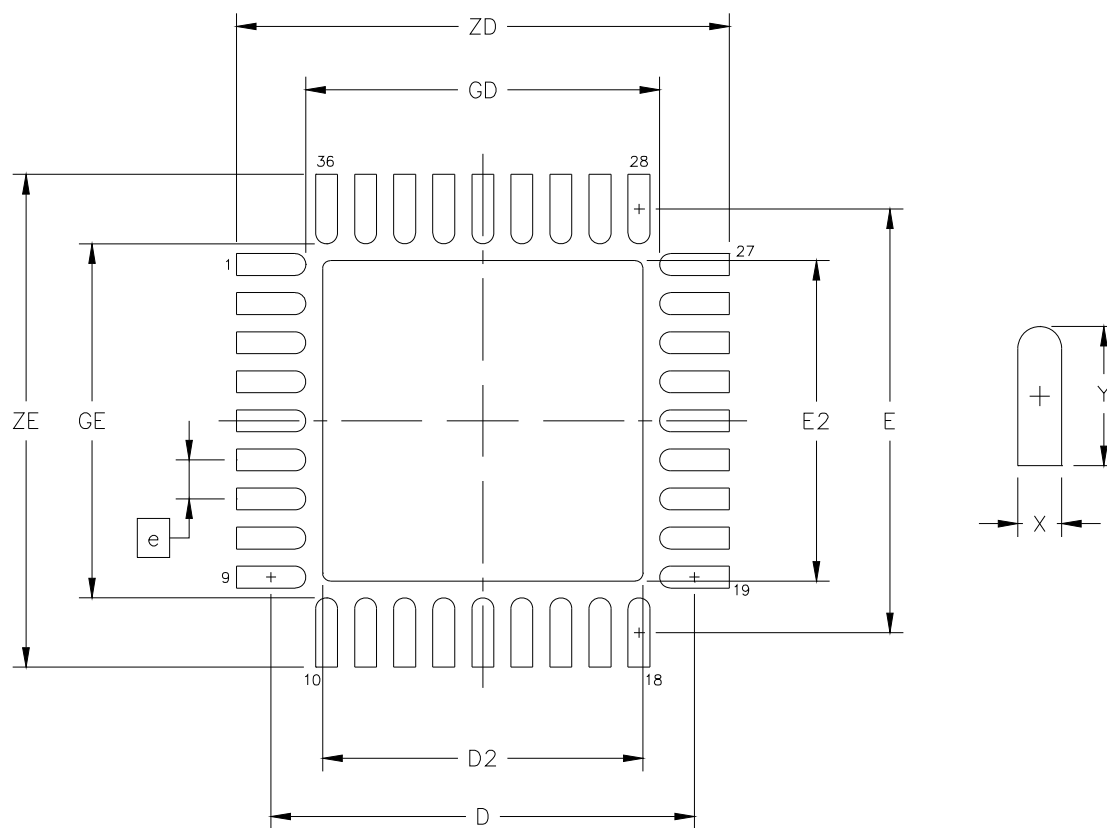


Figure 8. PCB Land Pattern Diagram

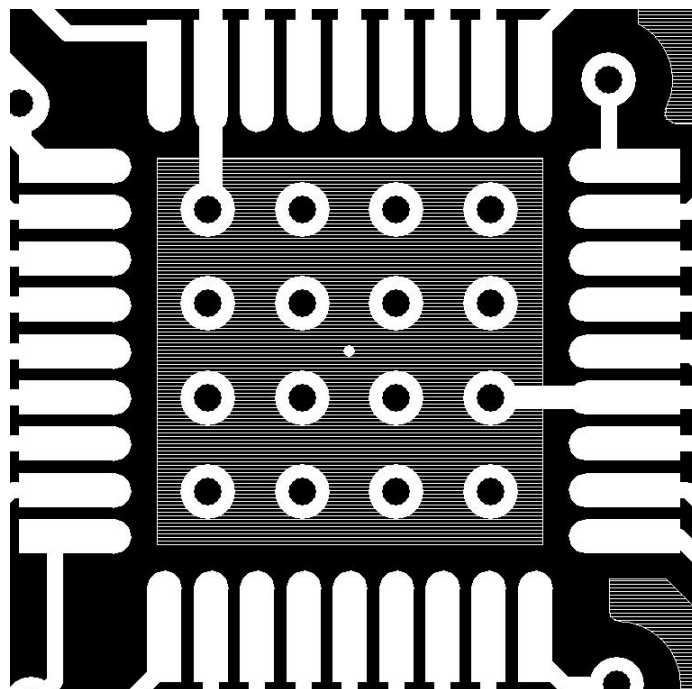


Figure 9. Ground Pad Recommended Layout

Table 13. PCB Land Pattern Dimensions

Dimension	MIN	MAX
e	0.50 BSC.	
E	5.42 REF.	
D	5.42 REF.	
E2	4.00	4.20
D2	4.00	4.20
GE	4.53	—
GD	4.53	—
X	—	0.28
Y	0.89 REF.	
ZE	—	6.31
ZD	—	6.31

Notes:**General**

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on IPC-SM-782 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

5. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μ m minimum, all the way around the pad.

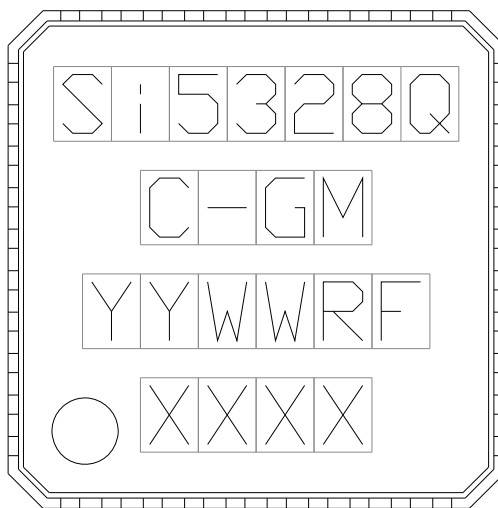
Stencil Design

6. A stainless steel, laser-cut, and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
7. The stencil thickness should be 0.125 mm (5 mils).
8. The ratio of stencil aperture to land pad size should be 1:1 for the perimeter pads.
9. A 4 x 4 array of 0.80 mm square openings on 1.05 mm pitch should be used for the center ground pad.

Card Assembly

10. A No-Clean, Type-3 solder paste is recommended.
11. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

11. Si5328 Device Top Mark



Mark Method:	Laser	
Font Size:	0.80 mm Right-Justified	
Line 1 Marking:	Si5328Q	Customer Part Number Q = Speed Code: C See "8.Ordering Guide" for options
Line 2 Marking:	C-GM	C = Product Revision G = Temperature Range –40 to 85 °C (RoHS6) M = QFN Package
Line 3 Marking:	YYWWRF	YY = Year WW = Work Week R = Die Revision F = Internal code Assigned by the Assembly House. Corresponds to the year and work week of the mold date.
Line 4 Marking:	Pin 1 Identifier	Circle = 0.75 mm Diameter Lower-Left Justified
	XXXX	Internal Code

DOCUMENT CHANGE LIST

Revision 0.9 to Revision 1.0

- Removed Vdd of 1.8 V.
- Updated lock and settling time specs.
- Added B speed grade with 808 MHz output frequency.

NOTES:

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